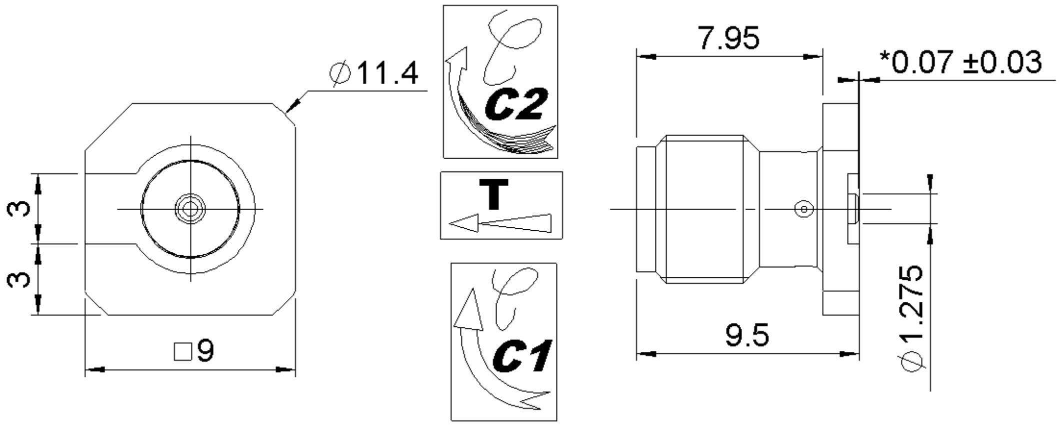
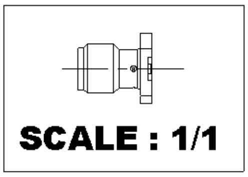
Technical Data Sheet

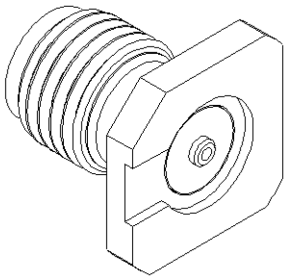
SMT RECEPTACLE PACK 100

PAGE **1/4**	ISSUE **1435B**	SERIES **SMA-COM**	PART NUMBER **R124427107**

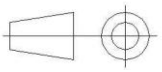
***Set back of c. contact from body**
(Retrait du c. central / au corps)







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NPGR**
Center contact	**BERYLLIUM COPPER**	**NPGR**
Outer contact	**-**	**-**
Insulator	**PTFE**	
Gasket	**-**	
Others parts	**-**	**-**
-	**-**	**-**
-	**-**	**-**

PACKAGING

Standard	Unit	Other
100	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-18**	GHz
VSWR	**1.14**	**+**	**0.0450**	x F(GHz) Maxi
Insertion loss			**0.05**	√F(GHz) dB Maxi
RF leakage		- (	**-**	- F(GHz)) dB Maxi
Voltage rating			**500**	Veff Maxi
Dielectric withstanding voltage			**1000**	Veff mini
Insulation resistance			**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**15**	N mini
Axial force – Opposite end	**15**	N mini
Torque	**1**	N.cm mini
Recommended torque		
Mating	**40**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**1.8080**	g

ENVIRONMENTAL

Operating temperature	**-65/+165**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

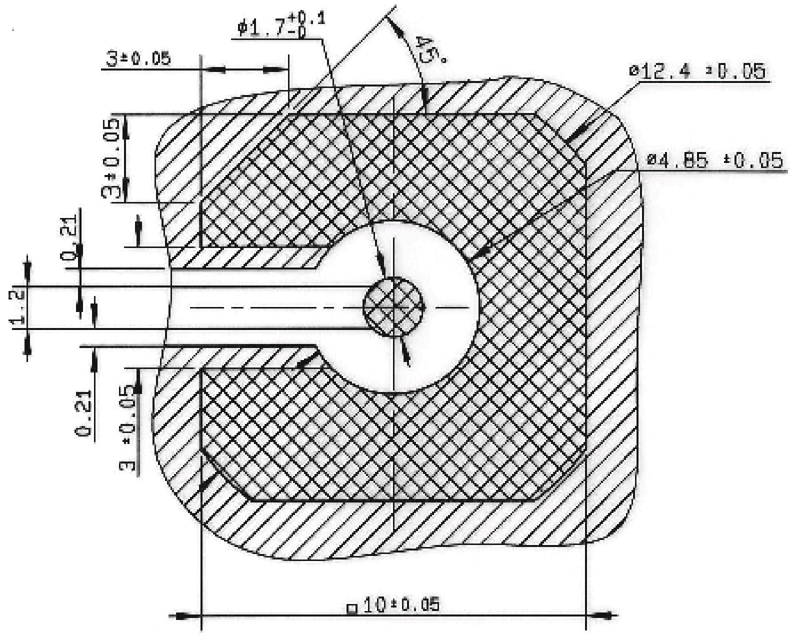
SPECIFICATION

OTHER CHARACTERISTICS

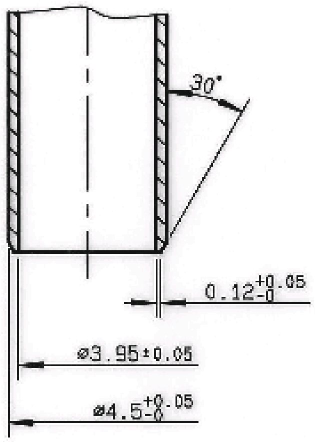
Assembly instruction:

Others:
FORCE F1:100N-TORQUES C1:90Ncm-C2:70Ncm

SMA B SERIES - INFORMATIONS



ASPIRATION PORT

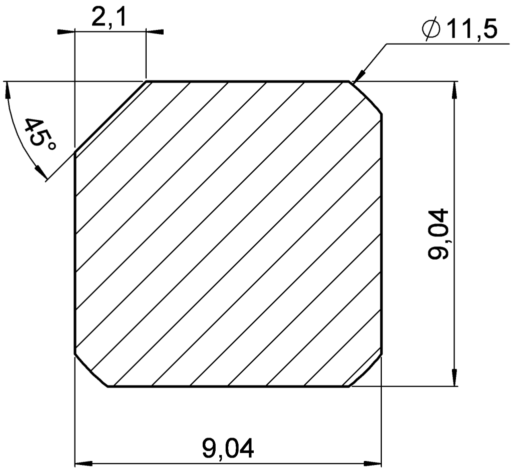


COPLANAR LINE
Pattern and signal are on the same side.
Thickness of PCB : .063 (1.6 mm)
The material of PCB is the epoxy resin of glass fabrics bacs. (Er = 4.8)
The solder resist should be printed except for the land pattern on the PCB.

▨ **Pattern**

▩ **Land for solder paste**

SHADOW OF SMA B

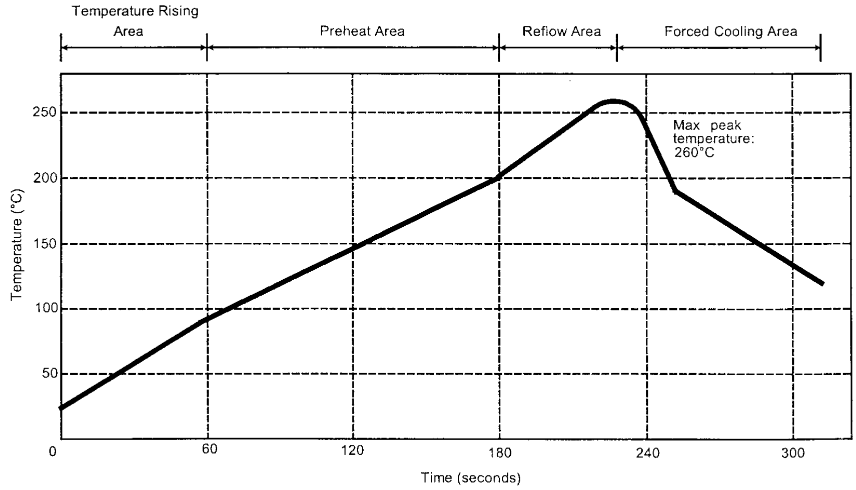


SOLDER PROCEDURE

1. Deposit solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.

   We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec